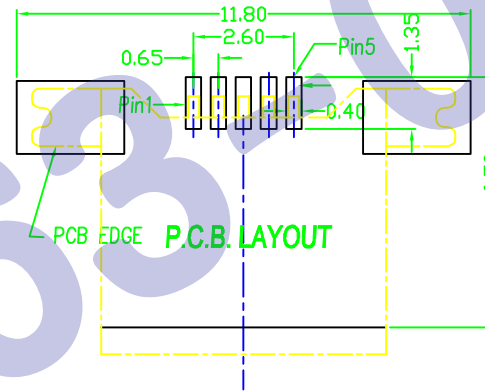
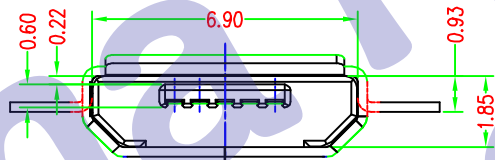
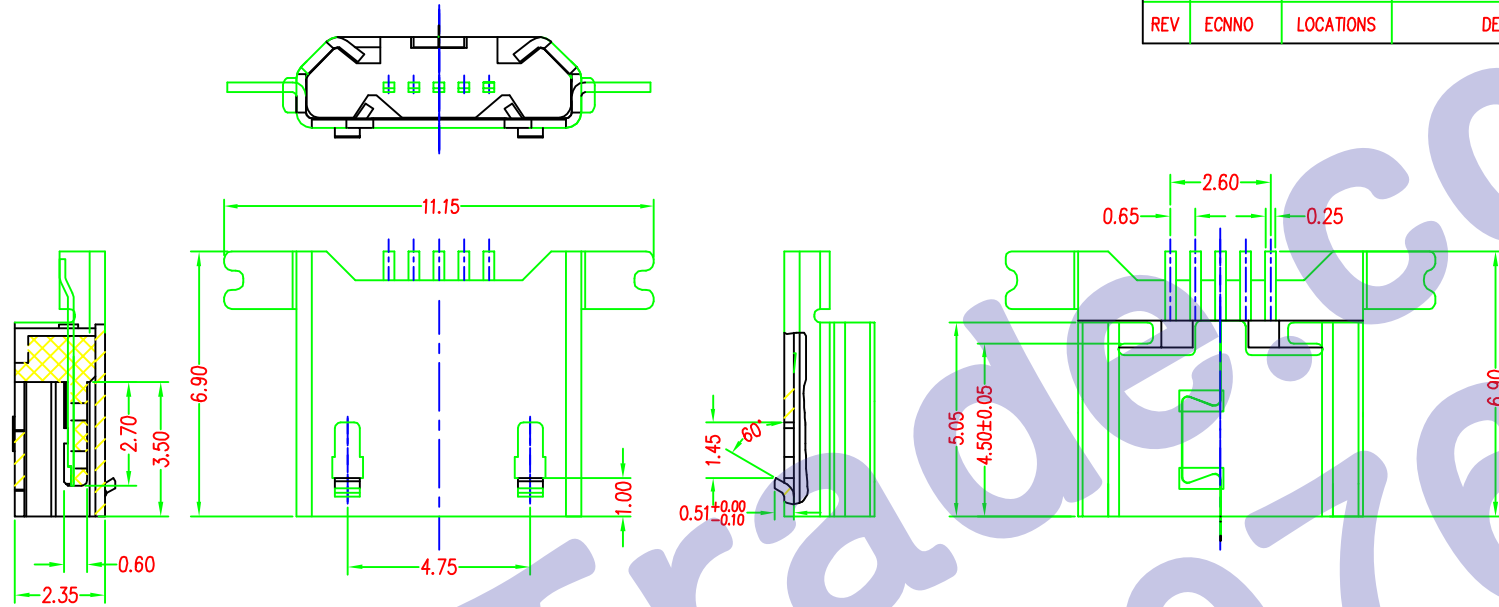


REV.	ECN NO	LOCATIONS	DESCRIPTION	DATE	REVSER	APPD
REV	ECNNO	LOCATIONS	DESCRIPTION	DATE	REVSEER	



RECOMMENDED PCB LAYOUT

Note:

1. Material:

1.1 Housing: High temperature thermoplastic with g.f, UL94v-0

1.2 Contact: copper alloy, t=0.20mm

1.3 Shell: copper alloy, t=0.25mm

2. Specification:

2.1 Current rating: 1 A Max.

2.2 Dielectric withstanding

voltage: 100 V(ac) for 1 min.

2.3 Contact resistance: 50 mΩ Max.

2.4 Insulation resistance: 100 MΩ Min.

2.5 Total mating force: 3.57 Kgf Max.

2.6 Total unmating force: 1.0 Kgf Min.0.81~2.05

Kgf Min.after 10000 insertion/extraction cycles

2.7 Temperature range: -30°C~80°C

PART NO:	PARTNO.	MATERIAL:	MATERIAL
MODEL NO:	MOLDNO.	FINSH:	FINISH
UNIT:	UNIT	COLOR:	COLOR
	SIZE:	DR:	DR
	SIZE:	CHK:	CHK
	SIZE:	APP:	APP
TOLERANCE UNSPECIFIED			
.x	.X		
.xx	.XX		
.xxx	.XXX		
ANG.	ANG.		

HDC有限公司

TITLE: Micro usb 5s7PinType (破板式)两只脚无导位Smt  
CUSTOMER DRAWING

DWG NO:	DWGNO	REV:	REV
SCALE:	SCALE	SHEET:	SHEET

3	Shell	1	N/A
2	Contact	5	N/A
1	Housing	1	N/A
No.	Name	Q'ty	Finish